| Contact Name Title - Contact Phone - Contact* Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product-Env | IPC ASSOCIATION ELECTRONICS | Material Composition © Copyright 2005. Il international and Par | osition De PC, Bannockl n-American co | claration ourn, Illinois. A opyright conver | Il rights reserved ntions. | under both | This docume level parts, the | ent is a declara he declaration | ation of the encompa | e substances sses all lowe | within the man | nufacture ls for whi | r listed item ch the man | . Note: if | the item is an as has engineering | ssembly with lov responsibility. |
|--|---|---|---|--|----------------------------|---------------------|---------------------------------|------------------------------------|-------------------------|-------------------------------|---------------------------------|---------------------------------|-----------------------------|----------------------------|--------------------------------------|-------------------------------------|
| Company name* Company unique ID | | | | | | e * | | | | | | s and Mfg l | nformatio | on | | |
| Donact Name Title - Contact Phone - Contact* Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U Manufacturing Proccess Information Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA O C 30 Seconds 3 | upplier | Information | | | | | | | | | | | | | | |
| Title - Contact Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product Enviro Compliance Phone - Representative* Product-Env-Stewards@onsemi.com Product-E | Company name* Company unique ID | | | | | Unique ID Authority | | | | |] | Response Date* | | | | |
| Product-Env-Stewards Authorized Representative* Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Requester Item Number Mfr Item Number Mfr Item Name Requester Item Number Manufacturing Site Weight* UOM U Annufacturing Proccess Information Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Product-Env-Stewards@onsemi.com NA | nsemi | | | | | | | | | | | | 2023-06-08 | | | |
| Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U Annufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA Phone - Representative* Phone - Representative* Phone - Representative* Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM U 2023-06-08 PHM 2162.35 mg E Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA O C 30 Seconds 3 | ontact Na | ame | | Title - Contac | et | |] | Phone - Contact* | | | | | Email - Contact* | | | |
| Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U LA9932UVC-XE IGNITER 2023-06-08 PHM 2162.35 mg E Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material Terminal Base Alloy Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 Seconds 3 | Product-E | Cnv-Stewards | | Product Envi | ro Compliance | | NA | | | | Product-Env-Stewards@onsemi.com | | | | | |
| Requester Item Number | Authorized Representative* Title - Representative | | | | |] | Phone - Representative* | | | |] | Email - Representative* | | | | |
| LA9932UVC-XE IGNITER 2023-06-08 PHM 2162.35 mg E Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles | Product-Env-Stewards Prod | | | | Product Enviro Compliance | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles | | Requester Item Number | Mfr Iten | Number | Mfr Item Name | | | Effective Dat | te Versi | on I | Manufacturing | Site | We | ght* | UOM | Unit Type |
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| Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3 | Ianufac | cturing Proccess Information | tion | | | | | | | | | | , | | | |
| | | Terminal Plating / Grid Array Material | | Terminal Base Alloy J-S | | J-STD-020 MS | SL Rating | Peak Pro | ocess Body | y Temperatu | e Max Time | Max Time at Peak Temperat | | re Number of Reflow Cycles | | cles |
| | | | | U Alloy NA | | NA | | 0 | | C | 30 | | seconds | 3 | | |
| omments | omments | | | · | | · · | · | | · | · · | | | · | | · | |

| RoHS Material Composition Declaration | | | Declaration 7 | Гуре * | Detailed |
|---|---|--|---|---|---|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | RoHS Definition: Quantity limit of 0.01% b (Pb), Mercury (Hg), Hexavalent Chromium phthalate (BBP), Dibutyl phthalate (DBP), I | (Cr6+), Polybrominated Biphenyls (PB | | | |
| contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided b | ed biphenyls and/or polybrominated diphenyl of an applicable quantity limit, please indicate fies that it gathered the information it provides n. Supplier acknowledges that Company will reverselied on informationprovided by others in a yothers, Supplier agrees that, at a minimum, i and the Supplier enter into a written agreement ource of the Supplier's liability and the Comp | ethers (each a "RoHS restricted substant be below which, if any, RoHS exemption in this form using appropriate method- ely on this certification in determining to completing this form, and that Supplier tssuppliers have provided certifications at with respect to the identified part, the any's remedies for issues that arise reg- | ce") in excess of the appli you believe may apply. If to ensure its accuracy and the compliance of its produce may not have independent regarding their contributions of the | cable quantity limit identified about the part is an assembly with low I that such information is true and cts with European Union membe ly verified such information. How ons to the part, and those certificant agreement, including any warrant. | ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not titions are at least as comprehensive as the anty rights and/or remedies provided as part of |
| RoHS Declaration * 4 - Item(s | does not contain RoHS restricted substances | per the definition above except for sele | ted exemptions | Supplier Acceptance | * Accepted |
| Exemption: 7c-I Electrical and electronic co | omponents containing lead in a glass or cera | mic other than dielectric ceramic in | apacitors, e.g. piezoelect | ronic devices, or in a glass or co | eramic matrix compound. |
| Exemption List Version | EL-2011/534/EU | | | | |
| Declaration Signature | | | | | |
| Instructions: Complete all of the required f Requester) and click on Submit Form to ha | | ccepted" on the Supplier Acceptance | drop-down. This will dis | play the signature area. Digital | lly sign the declaration (if required by the |
| Supplier Digital Signature Ra | astislav Drska | E_ | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|---------|-----------------|----------|---------------------------|------------------|--------|-----------|-----------------|
| Chip Parts | 74.52 | mg | | Epoxy resin | proprietary data | | 0.0224 | mg |
| | | | Supplier | Silver (Ag) | 7440-22-4 | | 4.3743 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 0.2534 | mg |
| | | | Supplier | Magnesium Monoxide (MgO) | 1309-48-4 | | 0.0149 | mg |
| | | | Supplier | Palladium (Pd) | 7440-05-3 | | 0.2832 | mg |
| | | | Supplier | Aluminum Trioxide (Al2O3) | 1344-28-1 | | 1.7065 | mg |
| | | | В | Nickel (Ni) | 7440-02-0 | | 6.7515 | mg |
| | | | Supplier | Gold (Au) | 7440-57-5 | | 0.0075 | mg |
| | | | A | Lead Oxide (PbO) | 1317-36-8 | 7c | 0.0075 | mg |
| | | | Supplier | Chromium Trioxide (Cr2O3) | 1308-38-9 | | 0.0075 | mg |
| | | | Supplier | Barium Titanate (BaO3Ti) | 12047-27-7 | | 57.7604 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 3.2267 | mg |
| | | | Supplier | Silica Crystalline (SiO2) | 14808-60-7 | | 0.1043 | mg |
| Die | 13.78 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 13.7511 | mg |
| | | | Supplier | Polyimide | Proprietary Data | | 0.0289 | mg |
| Die Attach | 2.93 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 1.0826 | mg |
| | | | Supplier | Epoxy resins | 129915-35-1 | | 0.1732 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 1.5336 | mg |
| | | | В | Antimony (Sb) | 7440-36-0 | | 0.1163 | mg |
| | | | Supplier | Polybutadiene polymer | Proprietary Data | | 0.0144 | mg |
| | | | В | Nickel (Ni) | 7440-02-0 | | 0.01 | mg |
| Lead Frame | 696.7 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 1.6024 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 0.9754 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 693.9132 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.209 | mg |
| Mold Compound-Black | 1367.94 | mg | | Epoxy Phenol Resin | proprietary data | | 296.0222 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 6.9765 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 1057.9647 | mg |
| | | | Supplier | Silica Crystalline (SiO2) | 14808-60-7 | | 6.9765 | mg |
| Plating | 4.14 | mg | В | Nickel (Ni) | 7440-02-0 | | 4.14 | mg |
| Protection coat | 2.0 | mg | | Polyimide | proprietary data | | 2 | mg |
| Wire Bond | 0.34 | mg | Supplier | Gold (Au) | 7440-57-5 | | 0.16 | mg |

| Supplier | Aluminum (Al) | 7429-90-5 | 0.18 | mg |
|----------|---------------|-----------|------|----|